

TANTALUM NITRIDE **Nanoparticles**

Quick Facts

Product Tantalum Nitride Nanoparticles

Stock No NS6130-12-000386

CAS 12033-62-4 **Form** Powder 99.9% **Purity**

APS 80-100nm



Tantalum nitride (TaN) is a chemical compound, a nitride of tantalum. Tantalum nitride is used to create barrier or "glue" layers between copper, or other conductive metals, and dielectric insulator films such as thermal oxides. Tantalum nitride (TaN) films have been shown to provide a barrier to copper diffusion while at the same time promoting good adhesion between the copper lines and the surrounding interlevel dielectric (ILD), the manufacture of integrated circuits, to create thin film surface mount resistors and has other electronic applications. It also has application in thin film resistors. It has the advantage over nichrome resistors of forming a passivating oxide film which is resistant to moisture.

Technical Specification

Molecular Formula TaN

Molecular Weight 194.95g/mol 14.30g/cm³ Density **Melting Point** 2700°C



Follow us:











APS 80-100nm

I www.nanoshel.com I sales@nanoshel.com



ISO 9001:2015 CERTIFIED COMPANY







INTELLIGENT MATERIALS PVT LTD

Derabassi Punjab (140507) INDIA

+91 9779 550077, 9779238252

NANOSHEL UK LIMITED

Chapel House, Chapel St Cheshire, CW12 4AB United Kingdom

NANOSHEL LLC 3422 Old Capitol Suit 1305 Wilmington DE - 19808 United States

+44 (0) 74 105 488, +44 203 137 5187

+1 646 470 4911